Product data sheet

1. General description

Planar passivated four quadrant triac in a SOT78D (IITO-220) internally insulated plastic package intended for use in general purpose bidirectional switching and phase control applications.

2. Features and benefits

- · High voltage capability
- · Least sensitive gate for highest noise immunity
- High junction operating temperature capability (T_{i(max)} = 150 °C)
- High minimum I_{GT} for guaranteed immunity to gate noise
- · Planar passivated for voltage ruggedness and reliability
- Triggering in all four quadrants
- Internally insulated package
- Isolated mounting base with 2500 V (RMS) isolation

3. Applications

- Applications subject to high temperature (T_{i(max)} = 150 °C)
- Compressor starting control circuits
- · General purpose motor controls
- General purpose switching

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values	Unit			
Absolute	Absolute maximum rating						
V_{DRM}	repetitive peak off-state voltage		600	V			
I _{T(RMS)}	RMS on-state current	full sine wave; $T_{mb} \le 112 ^{\circ}\text{C}$; Fig. 1; Fig. 2; Fig. 3	16	Α			
I _{TSM}	non-repetitive peak on- state current	full sine wave; $t_p = 20 \text{ ms}$; $T_{j(init)} = 25 \text{ °C}$; Fig. 4; Fig. 5	160	A			
		full sine wave; t_p = 16.7 ms; $T_{j(init)}$ = 25 °C	176	Α			
T _j	junction temperature		150	°C			

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Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics			·		
I _{GT}	gate trigger current	$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + G + T_j = 25 \text{ °C; } Fig. 7$	10	-	50	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + G T_j = 25 \text{ °C; } Fig. 7$	10	-	50	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; T2- G-} $ $T_j = 25 \text{ °C; } Fig. 7$	10	-	50	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2-\text{ G+} $ $T_j = 25 \text{ °C; } Fig. 7$	10	-	70	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 9</u>	-	-	60	mA
V _T	on-state voltage	I _T = 20 A; T _j = 25 °C; <u>Fig. 10</u>	-	1.22	1.5	V
Dynamic	characteristics					
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 402 V; T_{j} = 125 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit	500	-	-	V/µs
		V_{DM} = 402 V; T_{j} = 150 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit	400	-	-	V/µs
dI _{com} /dt	rate of change of commutating current	$V_D = 400 \text{ V; } T_j = 150 ^{\circ}\text{C; } I_{T(RMS)} = 16 \text{ A; } dV_{com}/dt = 20 ^{\circ}\text{V/}\mu\text{s; gate open circuit; } snubberless condition$	2	-	-	A/ms

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1		T2—T1
2	T2	main terminal 2		G sym051
3	G	gate		symoor
mb	n.c	mounting base; isolated	IITO-220 (SOT78D)	

6. Ordering information

Table 3. Ordering information

Type number	Package				
	Name	Description	Version		
BTA16-600B	IITO-220	Plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3 leads TO-220	IITO-220E		

7. Marking

Table 4. Marking codes

Type number	Marking codes
BTA16-600B	BTA16-600B

BTA16-600B

8. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V_{DRM}	repetitive peak off-state voltage		600	V
I _{T(RMS)}	RMS on-state current	full sine wave; $T_{mb} \le 112^{\circ}C$; <u>Fig. 1</u> ; <u>Fig. 2</u> ; <u>Fig. 3</u>	16	А
I _{TSM}	non-repetitive peak on- state current	full sine wave; t_p = 20 ms; $T_{j(init)}$ = 25 °C; Fig. 4; Fig. 5	160	А
		full sine wave; t_p = 16.7 ms; $T_{j(init)}$ = 25 °C	176	А
I ² t	I ² t for fusing	t _p = 10ms; sine wave	128	A ² s
dl _⊤ /dt	rate of rise of on-state current	I _G = 150mA	50	A/µs
I _{GM}	peak gate current		2	А
P _{GM}	peak gate power		5	W
P _{G(AV)}	average gate power	over any 20 ms period	0.5	W
T _{stg}	storage temperature		-40 to 150	°C
T _j	junction temperature		150	°C

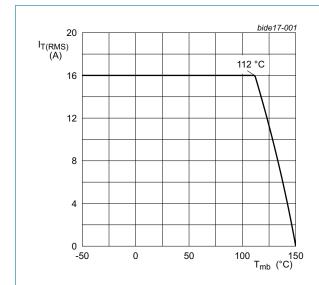
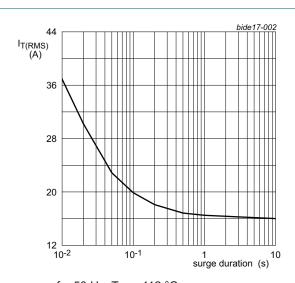


Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values



f = 50 Hz; T_{mb} = 112 °C Fig. 2. RMS on-state current as a function of surge duration; maximum values

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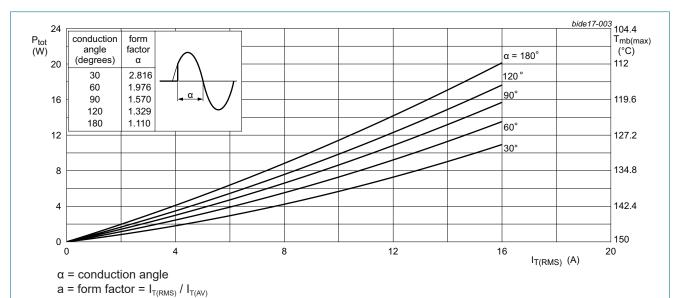


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

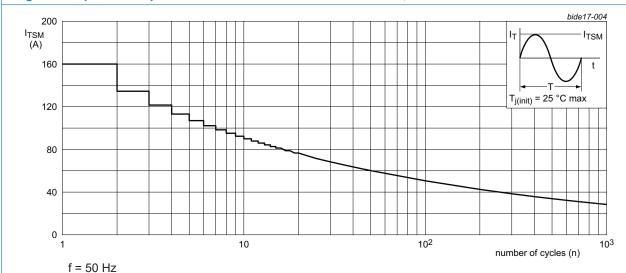


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

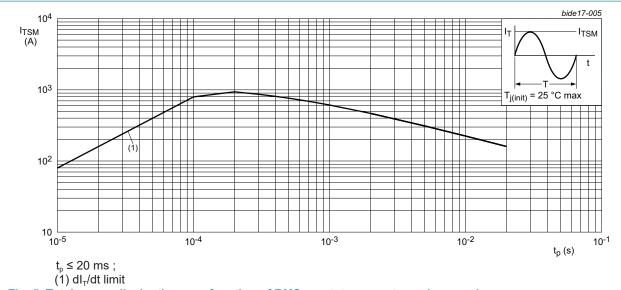


Fig. 5. Total power dissipation as a function of RMS on-state current; maximum values

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9. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R _{th(j-mb)}	thermal resistance from junction to mounting base	Fig. 6	-	-	1.9	K/W
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient free air	in free air	-	60	-	K/W

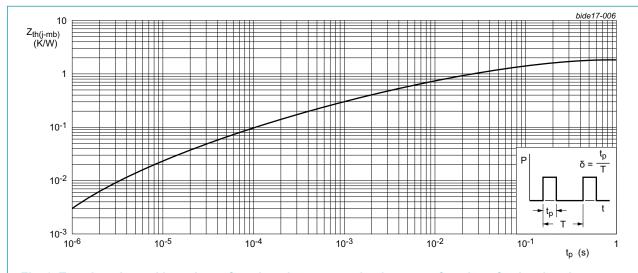


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Isolation characteristics

Table 6. Isolation characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{isol(RMS)}	RMS isolation voltage	50 Hz ≤ f ≤ 60 Hz; RH ≤ 65 %; from all pins to external heatsink; sinusoidal waveform; clean and dust free	-	-	2500	V
C _{isol}	isolation capacitance	from cathode to external heatsink	-	10	-	PF

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11. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics					
I _{GT}	gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T2+ G+;$ $T_j = 25 \text{ °C}; Fig. 7$	10	-	50	mA
		$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T2+ \text{ G-};$ $T_j = 25 \text{ °C}; Fig. 7$	10	-	50	mA
		$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T2- \text{G-};$ $T_j = 25 \text{ °C}; Fig. 7$	10	-	50	mA
		$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T2- G+;$ $T_j = 25 \text{ °C}; Fig. 7$	10	-	70	mA
l _L	latching current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T2+ G+; $ $T_j = 25 \text{ °C}; Fig. 8$	-	-	60	mA
		$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T2+ \text{ G-};$ $T_j = 25 \text{ °C}; Fig. 8$	-	-	90	mA
		$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; \text{ T2- G-};$ $T_j = 25 ^{\circ}\text{C}; \underline{\text{Fig. 8}}$	-	-	60	mA
		$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T2- G+; $ $T_j = 25 \text{ °C}; Fig. 8$	-	-	90	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 9</u>	-	-	60	mA
V_T	on-state voltage	I _T = 20 A; T _j = 25 °C; <u>Fig. 10</u>	-	1.22	1.5	V
V_{GT}	gate trigger voltage	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C};$ Fig. 11	-	0.7	1	V
		$V_D = 400 \text{ V}; I_T = 0.1 \text{ A}; T_j = 150 \text{ °C};$ Fig. 11	0.25	0.4	-	V
I _D	off-state current	V _D = 600 V; T _j = 25 °C	-	-	5	μA
		V _D = 600 V; T _j = 150 °C	-	0.4	2	mA
Oynamic o	characteristics		,			
dV _D /dt	rate of rise of off-state voltage	V_{DM} = 402 V; T_j = 125 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit	500	-	-	V/µs
		V_{DM} = 402 V; T_j = 150 °C; (V_{DM} = 67% of V_{DRM}); exponential waveform; gate open circuit	400	-	-	V/µs
dI _{com} /dt	rate of change of commutating current	V_D = 400 V; T_j = 150 °C; $I_{T(RMS)}$ = 16 A; dV_{com}/dt = 20 V/ μ s; gate open circuit; snubberless condition	2	-	-	A/ms

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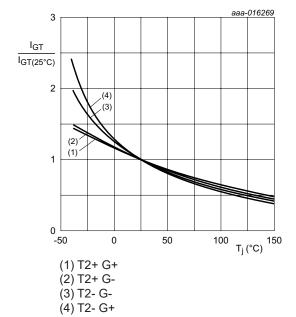


Fig. 7. Normalized gate trigger current as a function of junction temperature

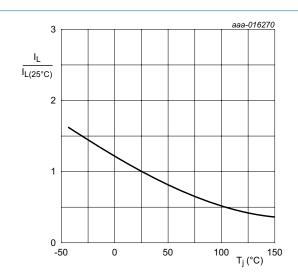


Fig. 8. Normalized latching current as a function of junction temperature

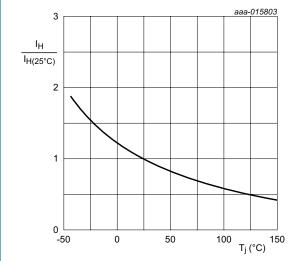
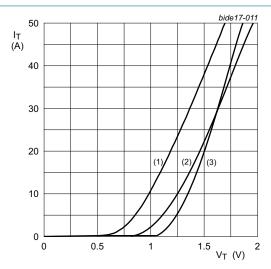


Fig. 9. Normalized holding current as a function of junction temperature



 $V_o = 1.053 \text{ V}; R_s = 0.0194 \Omega$

(1) T_i = 150 °C; typical values

(2) T_j = 150 °C; maximum values

(3) T_i = 25 °C; maximum values

Fig. 10. On-state current as a function of on-state voltage

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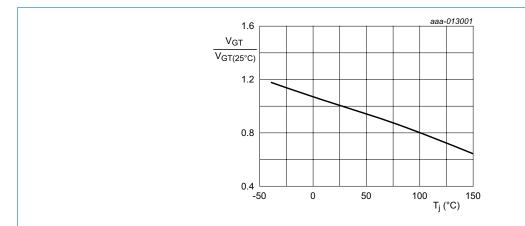
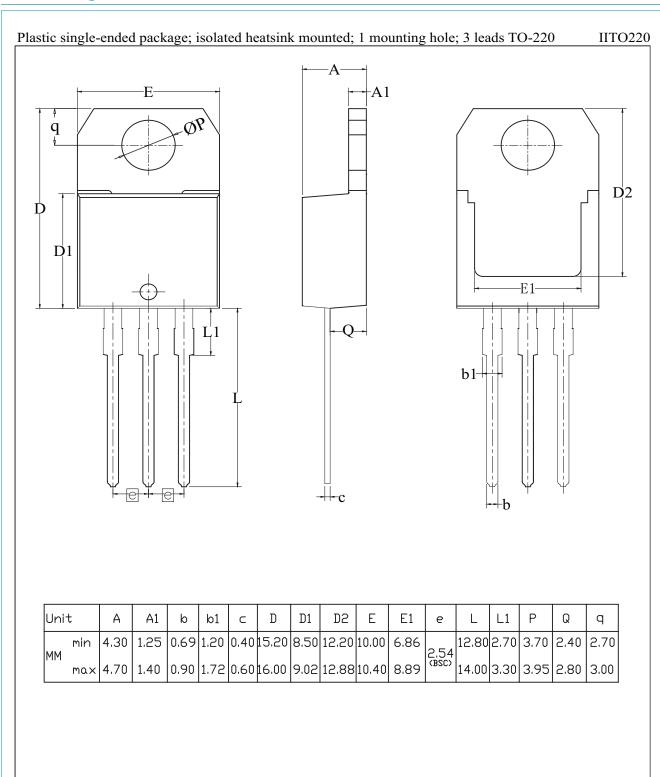


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

12. Package outline



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13. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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